

### AN3964 Application note

How to design a simple temperature measurement application using the STM32L-DISCOVERY

### 1 Introduction

This application note describes a method of implementing a simple application for temperature measurement using the STM32L-DISCOVERY. The solution described in this document uses the integrated temperature sensor of the STM32L1 microcontroller. The factory or user calibration method is described to improve the accuracy of the temperature sensor.

The demonstration application does not require any additional hardware. Once the STM32L-DISCOVERY board is updated with the associated firmware and is powered-up through a USB cable connected to the host PC, the application is ready to display the temperature of the STM32L1 microcontroller.

#### 1.1 Reference documents

- STM32L-DISCOVERY user manual (UM1079)
- STM32L-DISCOVERY Application note: Current consumption measurement and touch sensing demonstration (AN3413)
- STM32L151xx and STM32L152xx Flash and EEPROM programming (PM0062)
- STM32L151xx and STM32L152xx Ultralow power ARM-based 32-bit MCU with up to 128 Kbytes of Flash memory, RTC, LCD, USB, USART, I2C, SPI, timers, ADC, DAC, comparators datasheet

The above documents are available at http://www.st.com.

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### 2 Application overview

This section describes how the temperature sensor works and its measurements performed by the STM32L1 microcontroller embedded on the STM32L-DISCOVERY board.

A brief description of how the example temperature measurement application was implemented follows afterwards.

#### 2.1 Temperature sensor

The temperature sensor integrated in the STM32L microcontroller provides an analog output voltage proportional to the chip junction temperature of the device.

Note: Please note that the temperature information provided by sensor is the thermal chip junction temperature (actual temperature of semiconductor surface) and may differ from the ambient temperature. Please see section "Thermal characteristics" of product datasheet for more details.

The integrated temperature sensor provides reasonably linear characteristics with a deviation typically of  $\pm$  1% from linear asymptotic functions and a temperature range equal to that of the device (-40 °C to 85 °C) with a maximum junction temperature of 150 °C.

The sensor provides good linearity but quite poor interchangeability and must be calibrated to obtain good overall accuracy. If the application is designed to only measure the relative temperature variations, the temperature sensor does not need to be calibrated.

#### 2.2 Temperature measurement and data processing

The temperature sensor is internally connected to Channel 16 (ADC\_IN16) of the ADC (analog-to-digital converter) in the STM32L1 and is used to sample and convert the temperature sensor output voltage. The raw ADC data must be further processed to display the temperature in a standardized unit of measurement (Celsius, Farenheit or Kelvin).

The ADC reference voltage is connected to the 3V  $V_{DD}$  power supply of the STM32L-Discovery board. If the  $V_{DD}$  value is not accurately known, as in case of battery-operated applications, it must be measured in order to obtain a correct overall ADC conversion range. To easily measure the power supply voltage, we recommend using the embedded internal reference (bandgap) voltage. The precise voltage of the embedded bandgap is individually measured during the manufacturing process and stored in the protected memory area at address @1FF80078.

The embedded bandgap voltage calibration data is a 12-bit unsigned number (right-aligned bits, stored in 2 bytes) acquired by the STM32L1 ADC with a 3V ( $\pm$  10 mV) reference voltage. The accuracy of the factory measured bandgap calibration data is provided with an accuracy of  $\pm$  5 mV. Please see the datasheet for more details.



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#### 2.3 Application example description

Every 2 seconds the application acquires 16 samples from the temperature sensor voltage. The ADC raw data are filtered and averaged using an interquartile mean algorithm to reduce noise from the power supply system and the result is recalculated into standard units of temperature measurement (°C, in this example).

The LCD display is updated every 2 seconds either by ADC raw data or by the current temperature value in degrees Celsius. The user can switch between both temperature data representations by pressing the user button.

To demonstrate the low power capabilities of the STM32L1 ultra-low power microcontroller, the CPU is switched to Stop mode with the RTC (real-time clock) wake-up set to 2 seconds within the time interval between temperature sensor data measurements. The ADC data acquisition and data transfers are managed by direct memory access (DMA) while the CPU is in Low-power Sleep mode. The CPU is in Run mode at 16 MHz based on the HSI oscillator clock) only during the initialization phase and during the data processing period.



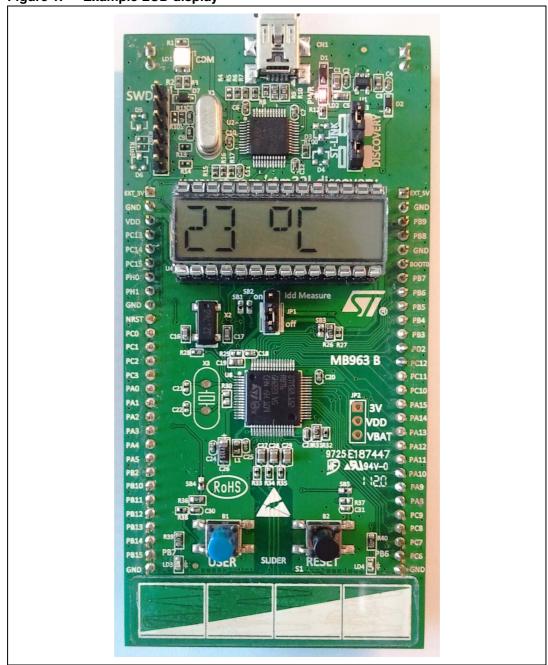


Figure 1. Example LCD display



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### 3 Getting started

Before getting started, the firmware must be updated and hardware configured as described in the following sections.

### 3.1 Setting up the board

#### Updating the firmware

The STM32L program memory needs to be updated with the firmware associated with this application note. For information on how to update the firmware, please read the 'readme.txt' file in the project folder.

#### Used hardware components

This application example uses the hardware components available on the STM32L-DISCOVERY board: the embedded peripherals of the STM32L microcontroller, the 6-digit LCD glass display and the user push-button. No additional components are required.

#### STM32L-DISCOVERY hardware settings

The I<sub>DD</sub> jumper JP1 must be placed in the ON position.

Both jumpers on CN3 must be fitted to enable communication between the STM32L microcontroller and the ST-Link debugging tool through the serial wire debug (SWD) interface.

Note: All solder bridges must be in their default state as described in UM1079.

#### 3.2 Using the demonstration application

It is very easy to start using the demonstration firmware.

When powered up, the temperature sensor application example first displays a welcome message before immediately displaying the current temperature in degrees Celsius with a 2-second refresh rate. When the User button is pressed once, the display shows the mean value of an array of 16 samples acquired by the ADC. One more press of the User button toggles between displaying the current temperature in degrees Celsius or the averaged value. The averaged value can be used later as a calibration point with a known temperature to improve overall accuracy of the temperature measurements.

#### 3.2.1 Temperature sensor calibration

The temperature sensor calibration data are stored during the manufacturing process in the protected memory area from where the user can read it and use it to improve the accuracy of the temperature measurements. The two-point calibration data is measured during production at ambient temperature 25 °C ( $\pm$  5°C) which is stored at address 0x1FF8007A and at hot temperature 110 °C ( $\pm$  5°C) which is stored at address 0x1FF8007E.

The temperature sensor calibration data is a 12-bit unsigned number (stored in 2 bytes) acquired by the STM32L1 ADC with a 3V ( $\pm$  10 mV) reference voltage.



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Note: The factory calibration data are available from revision "W" (cut 1.3) of STM32L15xx MCU devices. The user calibration can be used to workaround missing factory calibration data for the previous silicon revisions "Y" (cut 1.1) and "X" (cut 1.2).

The factory calibration data are tested for validity when the example application is initialized. If data is present in the memory, it is used for temperature calculation. Otherwise, the user calibration data stored during user calibration in EEPROM memory area is tested and used instead. If the user calibration data is not available either, the default values are used for calculation. The factory calibration or user calibration data provides good accuracy of the temperature measurement.

The use of the default calibration data, which is statistically based on the typical characteristics of the temperature sensor, may provide less accurate temperature estimations due to significant variations of the temperature sensor characteristics during the manufacturing process. It is recommended to use either the factory calibration data or to perform the two-point calibration of the temperature sensor, which respects the individual characteristics of the temperature sensor, to obtain reasonably accurate measurements.

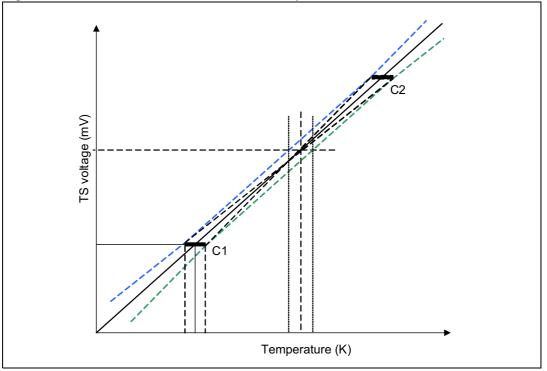


Figure 2. Transfer characteristics of the temperature sensor

The temperature can be evaluated from the digital value, VaITS, sampled by the ADC using linear approximation. It can be applied if the coordinates of two calibration points C1 and C2 are known as shown in *Figure 2*.

The current temperature can be evaluated as follows where the cold temperature coordinate pair is designated as (TC1, ValC1) and the hot temperature pair as (TC2, ValC2):

Temp = (TC2 - TC1) / (ValC2 - ValC1) \* (ValTS - ValC1) + TC1



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#### 3.3 Estimation of temperature sensor engineering tolerance

The two-point calibration method significantly improves the accuracy of the measurement as can be seen in *Figure 2*. The bias of the temperature measurement is mainly given by two sources; the temperature margin of the calibration points and the linearity of the sensor. Other sources of bias such as the ADC reference voltage margin can be effectively reduced. It can be neglected for factory calibrated values measured with the 3V ( $\pm$  10 mV) reference voltage.

The engineering tolerance of the temperature estimation is illustrated in *Figure 2* where it is limited by the two boundary lines of the minimum biased values (green) and the maximum biased values (blue). The area between the calibration points has a constant tolerance with a slight increase of the tolerance outside. For this reason, the recommended position of the calibration points should be as close as possible to the maximum and minimum values of the measurement range.

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### 4 Software description

#### 4.1 STM32L peripherals used by the application

This application example uses the following STM32L peripherals with the settings described below. For more information, please refer to the STM32L151xx datasheet.

#### Analog-to-digital converter (ADC)

The ADC performs analog-to-digital conversions of the internal reference voltage (4 samples) and of the temperature sensor voltage (16 samples) driven by DMA.

- ADC resolution: 12-bit
- ADC conversion mode: Scan mode driven by DMA
- ADC sampling time: 384 cycles

#### SysTick timer

The SysTick timer is used only to generate the delay needed for display refresh and is disabled during temperature measurements.

#### General-purpose inputs/outputs (GPIOs)

Ports C and E are connected to the User push-button and the LEDs.

- PB1 is set as an input floating pin with interrupt connected to User push-button
- PB7 (green LD3) and PB6 (blue LD4) are set as an output push-pull.
- During low power modes, I/Os are placed in analog input mode to reduce power consumption except for a few pins related to the hardware interface (PB7 - green LD3 and PB6 - blue LD4). It means that all Schmitt triggers on unused standard I/O pins are disabled to reduce power consumption.

#### LCD controller

The several functions available in the firmware library for the liquid crystal display (LCD) are used to initialize, clear, display strings and scroll messages needed in the application code.

#### Clocks

The high-speed internal (HSI) RC oscillator is selected as the main clock source.

The application manages the peripheral clocks depending on the selected powersaving mode. When the device enters Stop mode, the multi-speed internal (MSI) RC oscillator is switched OFF and the low-speed external crystal (LSE) acts as the clock source until the device is woken-up by an external event. When exiting Low Power Run mode, the MCU switches the MSI oscillator back ON. The LSE is only switched ON during Manufacturing Test mode to check its functionality.



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#### 4.2 STM32L15x standard firmware library configuration

The *stm32l*1xx\_conf.h file of the STM32L standard firmware library allows you to configure the library by enabling the peripheral functions used by the application.

The header files of the library modules are included in the *stm32l*1xx\_conf.h file as listed below:

- #include stm32l1xx\_adc.h
- #include stm32l1xx\_exti.h
- #include stm32l1xx\_flash.h
- #include stm32l1xx\_gpio.h
- #include stm32l1xx\_syscfg.h
- #include stm32l1xx\_lcd.h
- #include stm32l1xx\_pwr.h
- #include stm32l1xx\_rcc.h
- #include stm32l1xx\_rtc.h
- #include misc.h

The corresponding library modules must be included in the project for successful compilation and linking.

### 5 Conclusion

This application note shows how to use the STM32L1 integrated temperature sensor embedded in your STM32L-DISCOVERY.

The firmware example associated with this application note allows you to explore the temperature sensing capability of STM32L1xx microcontrollers and at the same time demonstrate its ultra low-power features. It can be used as a starting point for your own development.

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### 6 Revision history

#### Table 1.Document revision history

Date	Revision	Changes
27-Sep-2011	1	Initial release.



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